

FIGURE 1

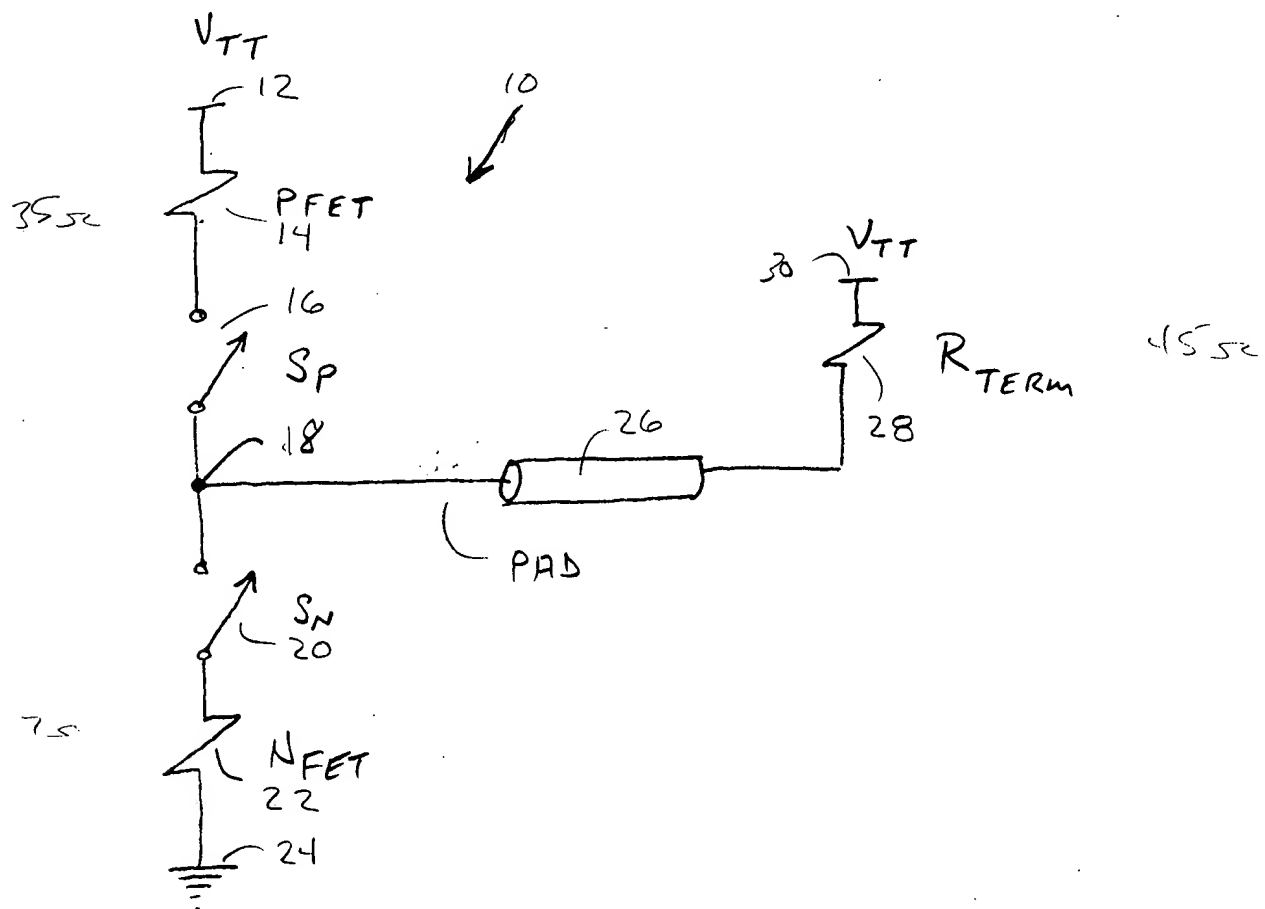


FIGURE 2A

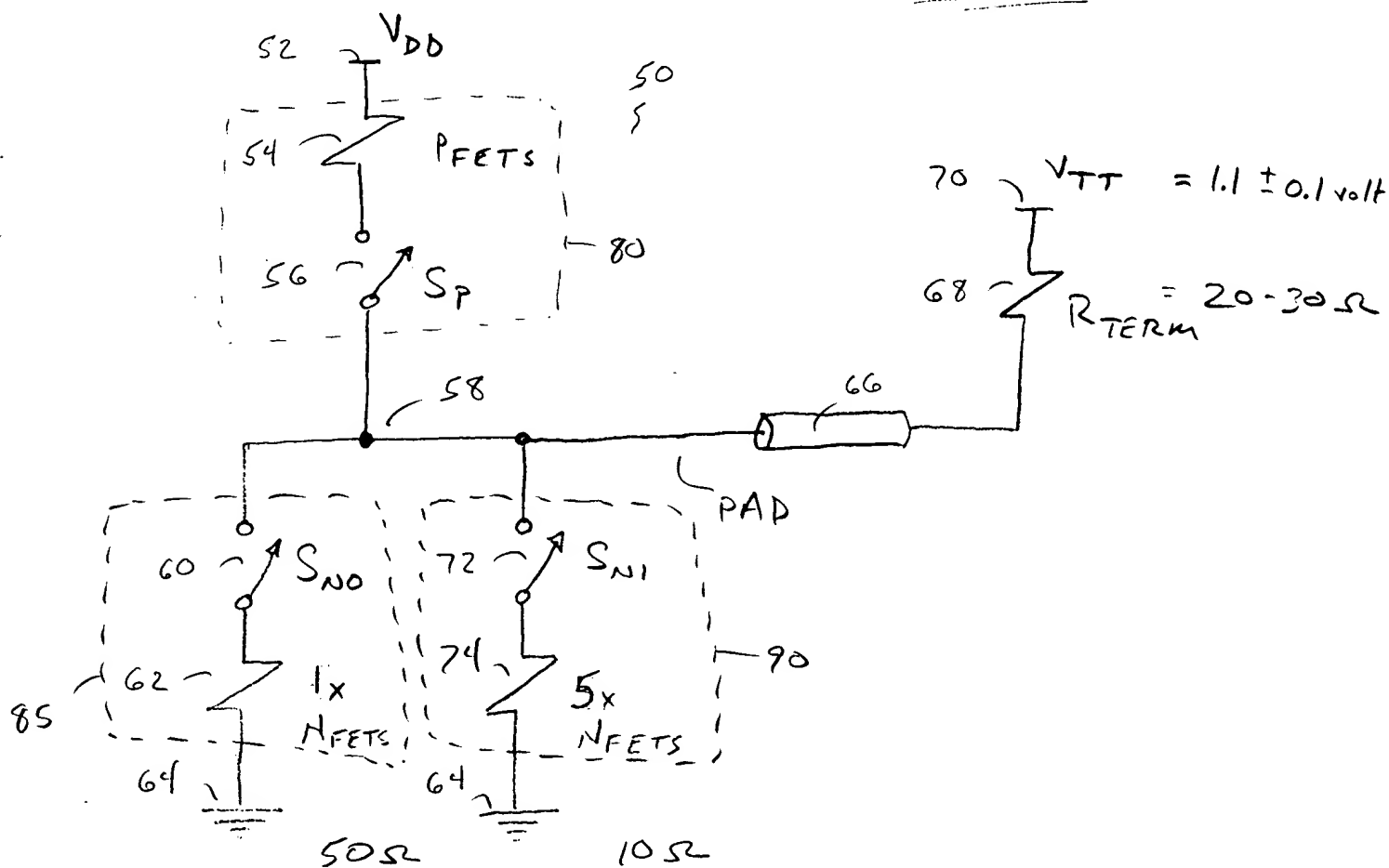


FIGURE 2B

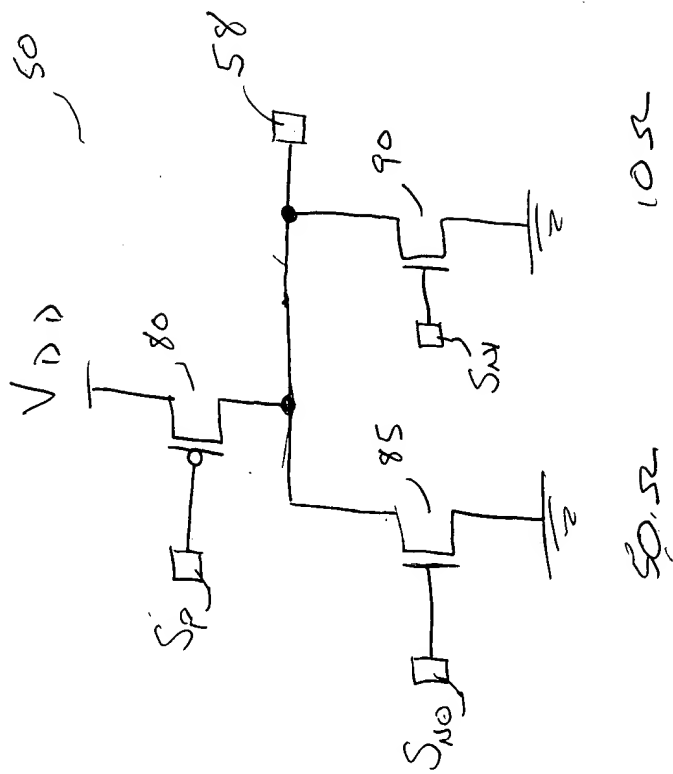
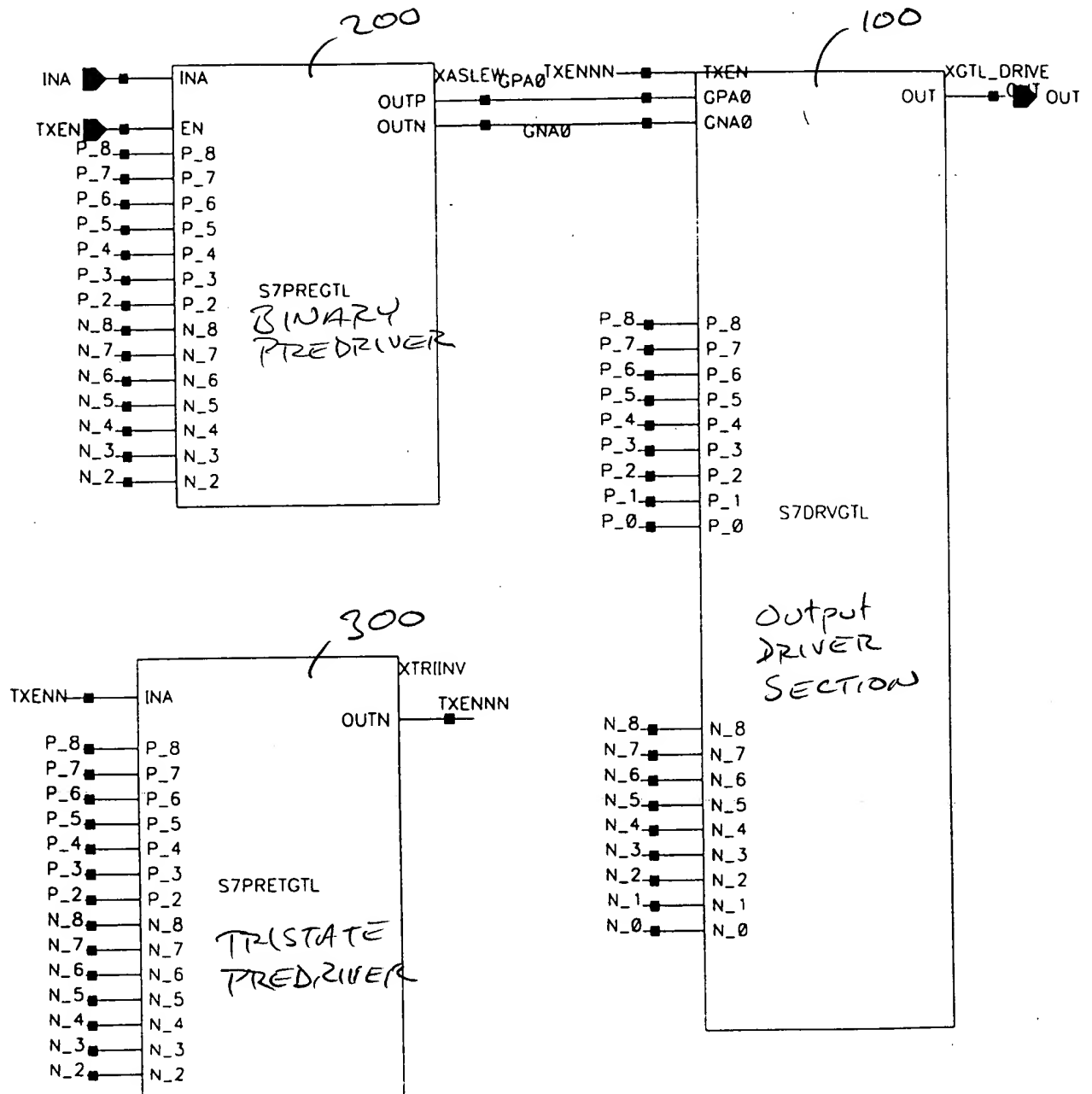
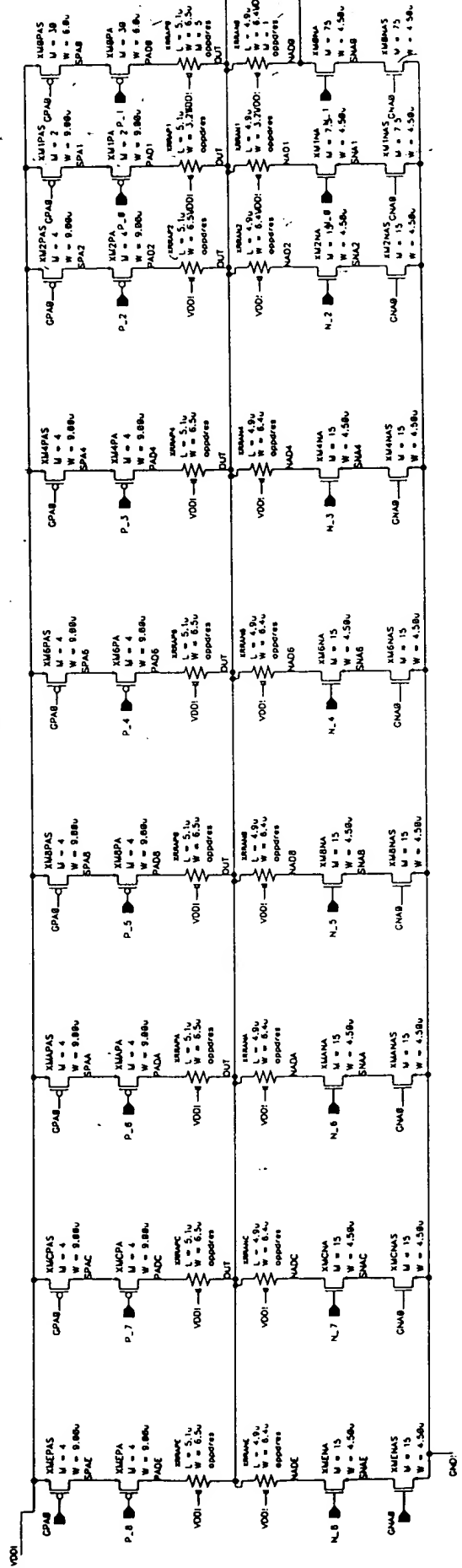


FIGURE 3



24 48

Sp
105
S₂₁



105
S₂₀

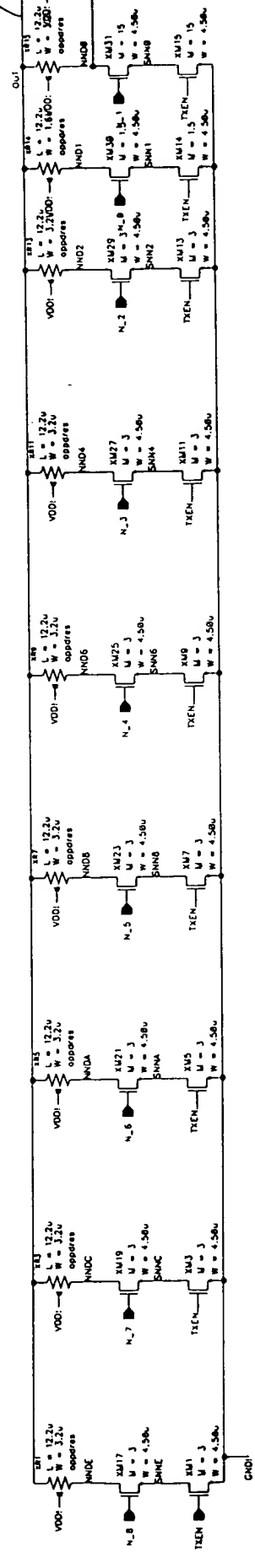


FIGURE 4A

FIGURE 4B

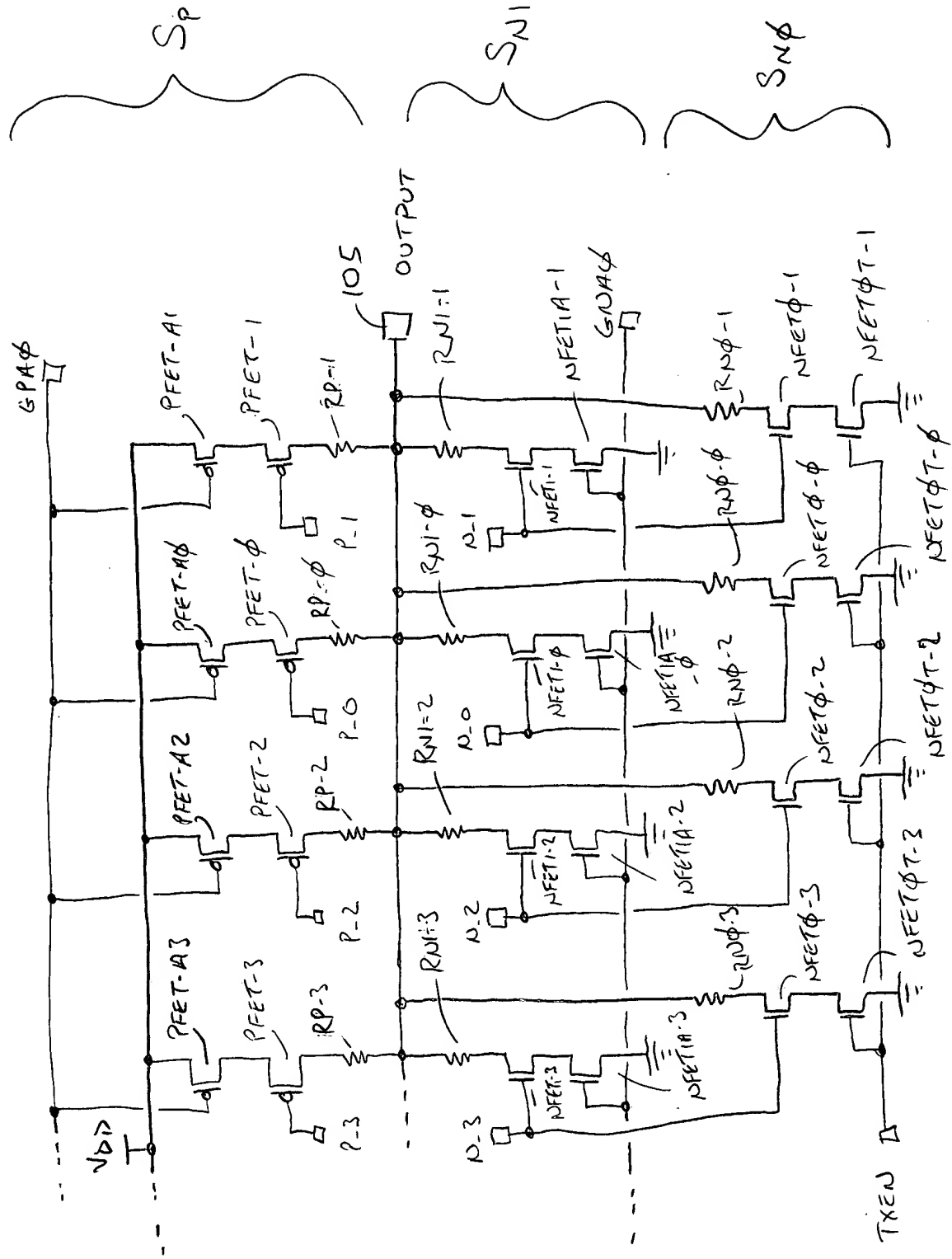
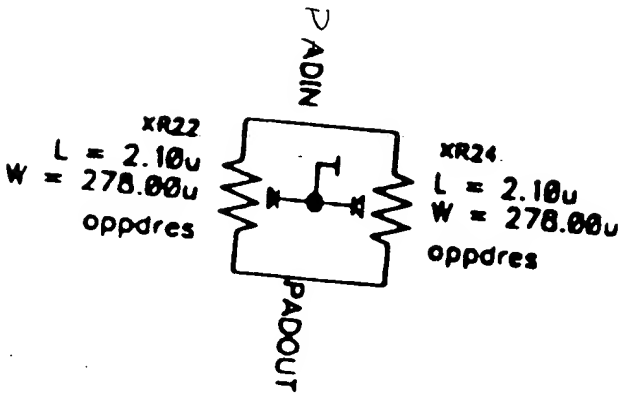
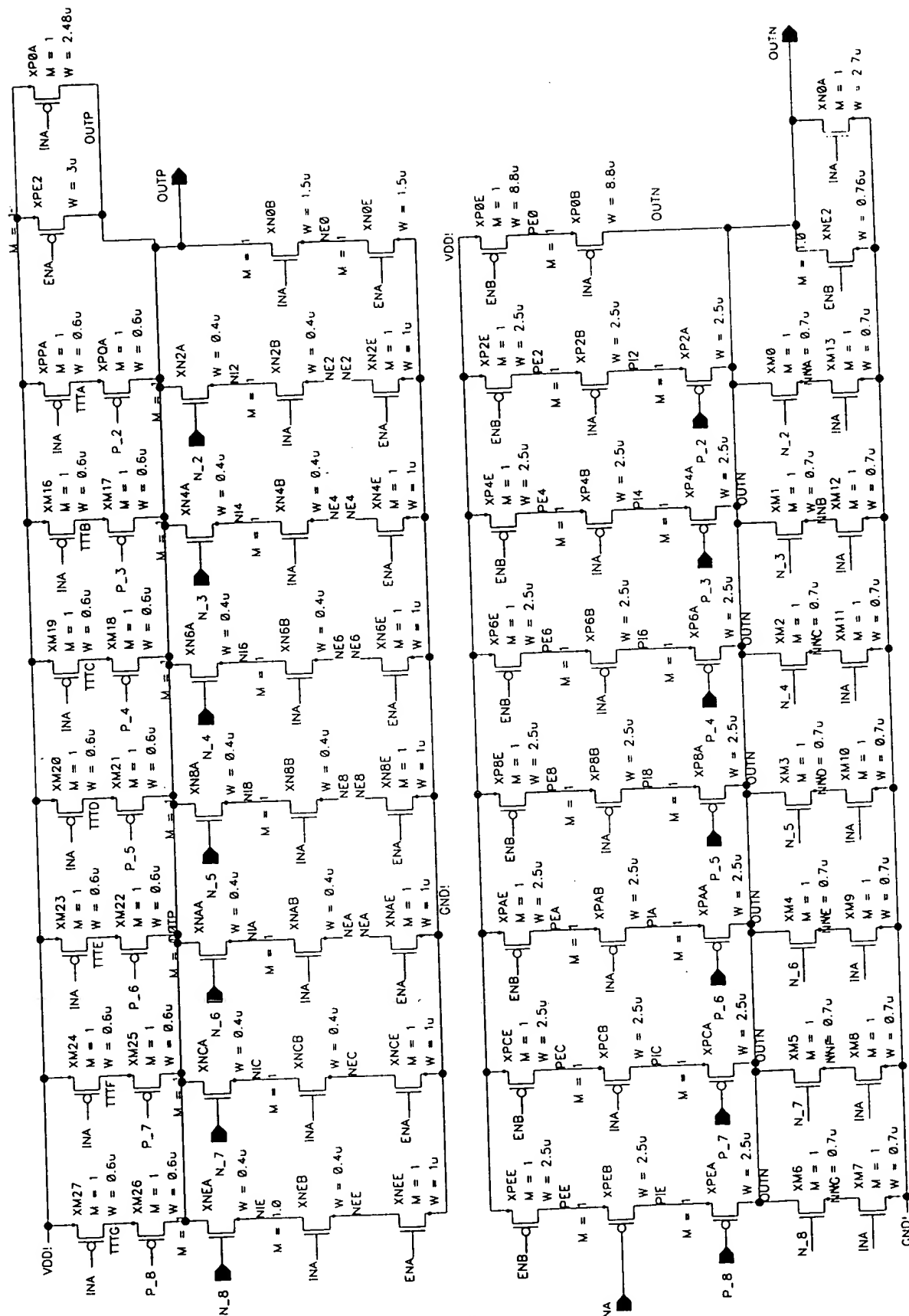


FIGURE 5



SELECTABLE OP RESISTORS TO BE USE WITH PADXFER METAL (LM) TOTAL RESISTENT MATCHING UP TO 3 OHMS.

- ONE RESISTORS L=2.1U AND W=93.0U = 3.0 OHMS
 - ONE RESISTORS L=2.1U AND W=111.0U = 2.5 OHMS
 - ONE RESISTORS L=2.1U AND W=139.0U = 2.0 OHMS
 - ONE RESISTORS L=2.1U AND W=185.0U = 1.5 OHMS
 - ONE RESISTORS L=2.1U AND W=278.0U = 1.0 OHMS
 - TWO RESISTORS L=2.1U AND W=278.0U IN PARALLEL = 0.5 OHMS SHOWN
- USE OF 0.5 OHMS RESISTORS TO BE USED FOR 0 OHMS

[illegible]

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FIGURE 8

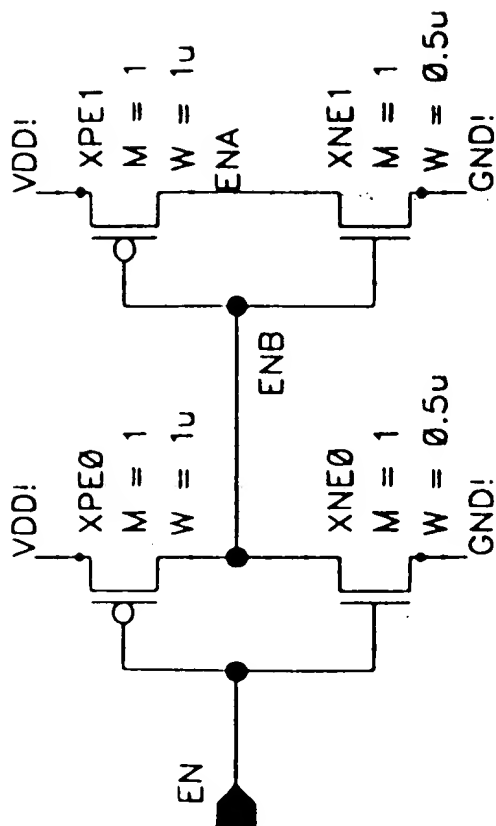


FIGURE 9A

Uncompensated

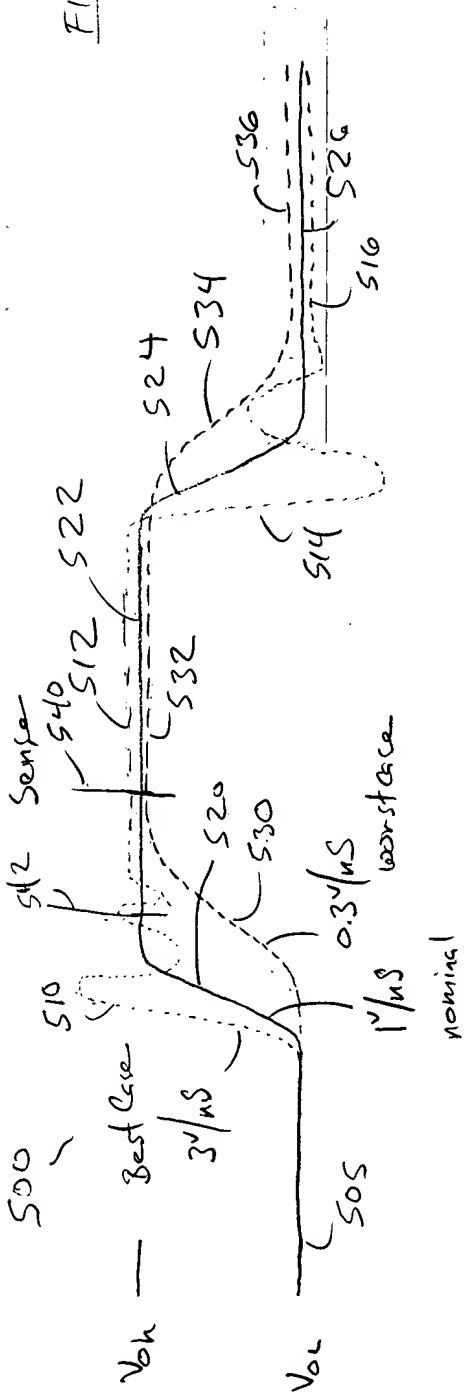


FIGURE 9B

Compensated

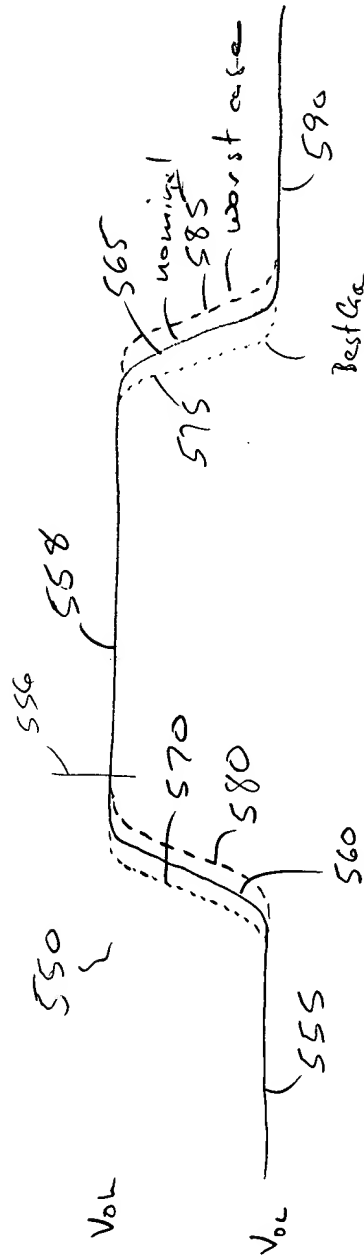
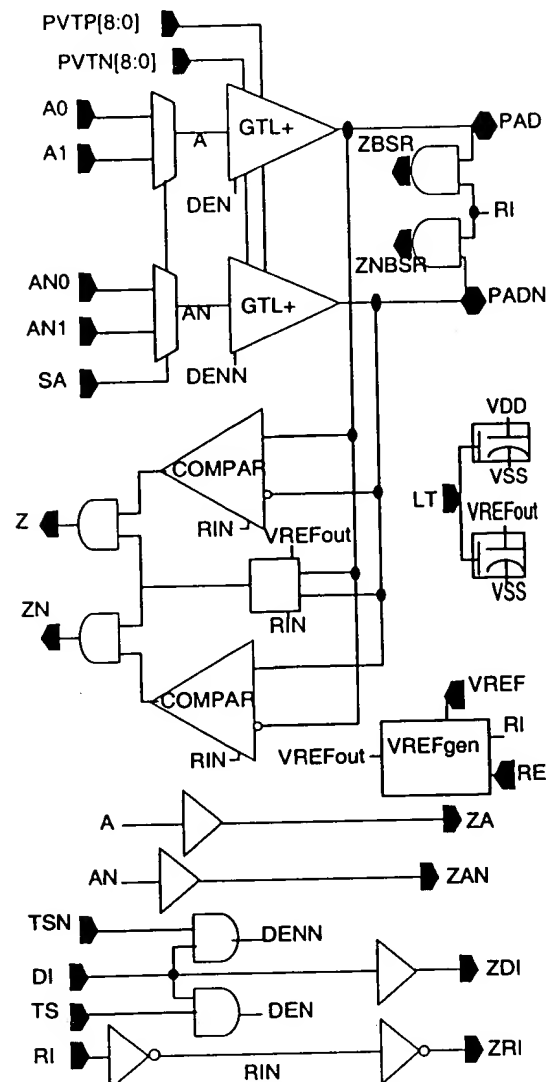


FIGURE 10

Description:

Non-inverting bidirectional driver/receiver that interfaces 1.8V internal functions with 1.1V enhanced GTL+ off-chip bidirectional data bus. The driver operates with a 1.8V supply. The driver has off-chip termination of 45 ohm to 1.1V (V_{TT}) at each end of the bus (double termination). The receiver has external reference V_{ref} ($V_{TT} \cdot 2/3$).

A0	Driver data0 input
A1	Driver data1 input
AN0	Driver data0 input
AN1	Driver data1 input
SA	Driver data select input
DI	Driver inhibit input (DI in)
TS	In-Phase Driver three-state control
TSN	Out-Phase Driver three-state control
PVTP[8:0]	PMOS edge rate control bus input
PVTN[8:0]	NMOS impedance control bus input
RE	Reference enable
RI	Receiver inhibit input (RI in)
VREF	($V_{TT} \cdot 2/3$) input signal
PAD	In-Phase Driver output/receiver input
PADN	Out-Phase Driver output/receiver input
ZDI	Driver inhibit output (DI out)
ZRI	Receiver inhibit output (RI out)
Z	In-Phase Receiver output
ZN	Out-Phase Receiver output
ZA	Data0 test output (A0 or A1 out)
ZAN	DataN0 test output (AN0 or AN1 out)
ZBSR	PAD test output (PAD out)
ZNBSR	PADN test output (PADN out)
LT	Leakage test input



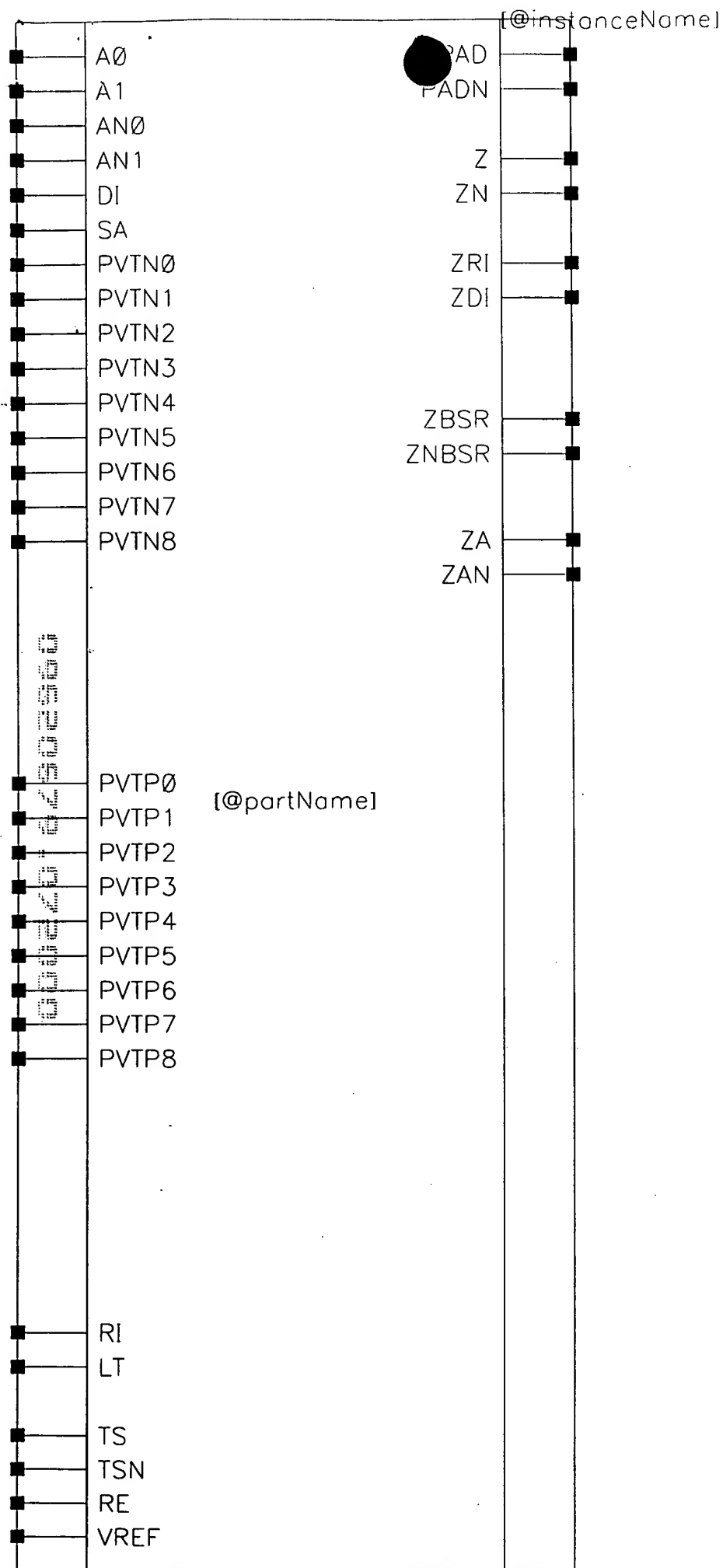


FIGURE 12

Driver Truth Table

Inputs							Outputs	
A0	A1	SA	TS	DI	PVTP	PVTN	PAD	Comments
-	-	-	0	-	-	-	Hi-Z ¹	High impedance mode
-	-	-	-	0	-	-	Hi-Z ¹	High impedance mode
-	-	-	-	-	0 ²	0 ²	Hi-Z ¹	PVT Test mode
0	-	0	-	-	-	0 ²	Hi-Z ¹	PVT Test mode
1	-	0	-	-	0 ²	-	Hi-Z ¹	PVT Test mode
0	-	0	1	1	-	>0	0 ³	PVT Test mode ³
1	-	0	1	1	>0	-	1 ³	PVT Test mode ³
0	-	0	1	1	>0	>0	0 ³	Functional, A0 data mode
0	-	0	1	1	1	1	0 ³	Functional, 10 Ohms @ BC
0	-	0	1	1	4	4	0 ³	Functional, 10 Ohms @ NOM
0	-	0	1	1	8	8	0 ³	Functional, 10 Ohms @ WC
1	-	0	1	1	>0	>0	1 ³	Functional, A0 data mode
-	-	1	1	1	>0	>0	A1	Functional, A1 data mode

¹ PAD is at "V_{TT}" when connected to off-chip terminator.

² When PVT= 0 all PVT bits go to vss and are off.

³ PAD Logical "1" = V_{tt} = 1.1V, Logical "0" = 0.4v or less

Notes: A. V_{dd}=1.8(+/- 0.1)V, V_{tt} = 1.1(+/- 0.02)V

B. During module external I/O test and system mode, driver output pullup is made by the external 22.5 ohm resistor to V_{tt}.

C. NDR will be based on driver terminated off-chip.

D. A0, A1, AN0, and AN1 are independent from each other

E. Entries in columns PVTP, PVTN represent number of lines held at logic "1" state. For testing the Impedance Controller forces PVTP and PVTN to 4 (i.e. PVTP[8:0]=PVTN[8:0]=[000011110] for all supply voltage levels.

Driver Truth Table

Inputs							Outputs	
AN0	AN1	SA	TSN	DI	PVTP	PVTN	PADN	Comments
-	-	-	0	-	-	-	Hi-Z ¹	High impedance mode
-	-	-	-	0	-	-	Hi-Z ¹	High impedance mode
-	-	-	-	-	0 ²	0 ²	Hi-Z ¹	PVT Test mode
0	-	0	-	-	-	0 ²	Hi-Z ¹	PVT Test mode
1	-	0	-	-	0 ²	-	Hi-Z ¹	PVT Test mode
0	-	0	1	1	-	>0	0 ³	PVT Test mode ³
1	-	0	1	1	>0	-	1 ³	PVT Test mode ³
0	-	0	1	1	>0	>0	0 ³	Functional, A0 data mode
0	-	0	1	1	1	1	0 ³	Functional, 10 Ohms @ BC
0	-	0	1	1	4	4	0 ³	Functional, 10 Ohms @ NOM
0	-	0	1	1	8	8	0 ³	Functional, 10 Ohms @ WC
1	-	0	1	1	>0	>0	1 ³	Functional, A0 data mode
-	-	1	1	1	>0	>0	A1	Functional, A1 data mode

¹. PAD is at "V_{TT}" when connected to off-chip terminator.

². When PVT= 0 all PVT bits go to vss and are off.

³. PAD Logical "1" = V_{tt} = 1.1V, Logical "0" = 0.4v or less

Notes: A. V_{dd}=1.8(+/- 0.1)V, V_{tt} = 1.1(+/- 0.02)V

B. During module external I/O test and system mode, driver output pullup is made by the external 22.5 ohm resistor to V_{tt}.

C. NDR will be based on driver terminated off-chip.

D. A0, A1, AN0, and AN1 are independent from each other

E. Entries in columns PVTP, PVTN represent number of lines held at logic "1" state. For testing the Impedence Controller forces PVTP and PVTN to 4 (i.e. PVTP[8:0]=PVTN[8:0]=[000011110] for all supply voltage levels.

FIGURE 14

Driver Propagation Delays (no load on outputs).

Path (Input to Output)	Performance Level	Parameter	Delay (ns) = Intercept + slope (D_{std}) ¹		$V_{dd} = 1.92V$ $V_{tt} = 1.12V$ $T_j = 25^\circ C$ Process = Fast
			$V_{dd} = 1.72V$ $V_{tt} = 1.08V$ $T_j = 100^\circ C$ Process = Slow	$V_{dd} = 1.8V$ $V_{tt} = 1.13V$ $T_j = 60^\circ C$ Process = Nom.	
A0-PAD	A	t_{PLH}	1.2 ns	1.0 ns	0.8 ns
		t_{PHL}	1.2 ns	1.0 ns	0.8 ns
AN0-PADN	A	t_{PLH}	1.2 ns	1.0 ns	0.8 ns
		t_{PHL}	1.2 ns	1.0 ns	0.8 ns

1. D_{std} is the number of standard loads.

2. Voltage at the package pin.

3. Design is optimized for $V_{tt}=1.1v$ can be used for $V_{tt}=1.0v$ to $1.2v$.

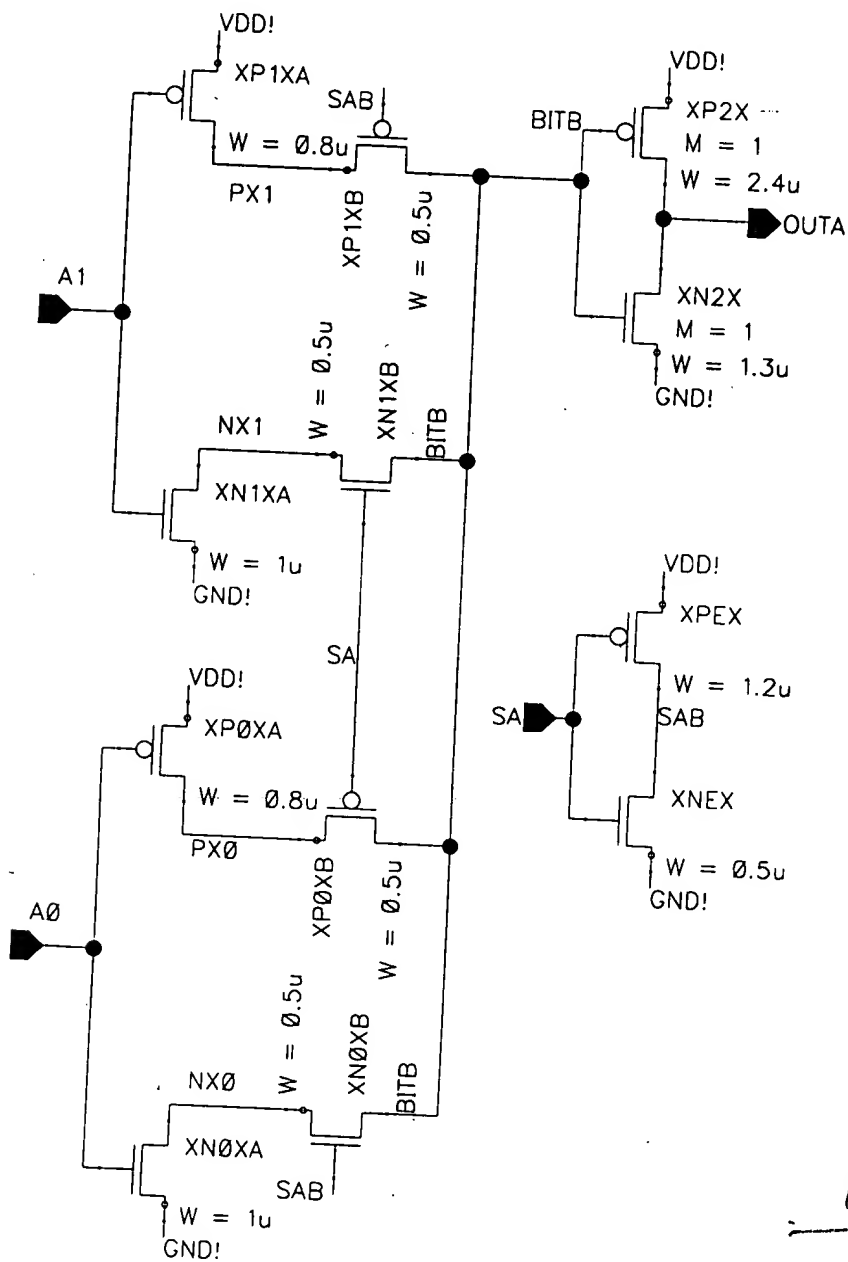


FIGURE 15